Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2843

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain—source ON resistance : R_{DS} (ON) = 0.54 Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 9.0 \text{ S}$ (typ.) • Low leakage current : $I_{DSS} = 100 \mu A$ (max) ($V_{DS} = 600 V$)

• Enhancement-mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	600	V
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	600	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	10	Α
	Pulse (Note 1)	I _{DP}	40	Α
Drain power dissipatio	n (Tc = 25°C)	P _D	45	W
Single pulse avalanche energy (Note 2)		E _{AS}	363	mJ
Avalanche current		I _{AR}	10	Α
Repetitive avalanche energy (Note 3)		E _{AR}	5.0	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C

Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C / W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 6.36 mH, R_G = 25 Ω , I_{AR} = 10 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.



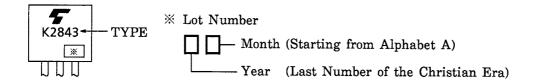
Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold v	voltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 5 A	_	0.54	0.75	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 5 A	3.0	9.0	_	S
Input capacitano	e	C _{iss}		_	2040	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	230	_	pF
Output capacitance		C _{oss}			590	_	
Switching time	Rise time	t _r	V_{GS} V_{OUT} V_{OUT} V_{OUT} V_{DD} V_{OUT}	_	22	_	- ns
	Turn-on time	t _{on}		1	58	1	
	Fall time	t _f		-	36		
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$	-	190		
Total gate charg plus gate-drain)		Qg			45		
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		25	_	nC
Gate-drain ("miller") Charge Qg		Q_{gd}			20	_	

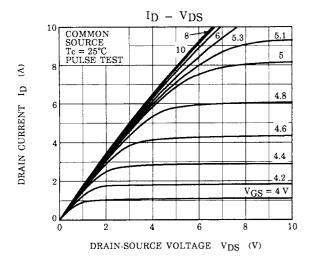
Source-Drain Ratings and Characteristics (Ta = 25°C)

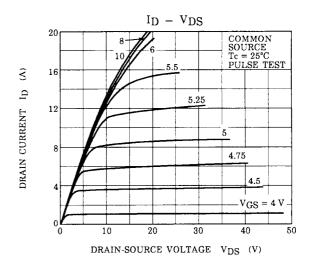
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	1	1	10	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_		40	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 10 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 10 A, V _{GS} = 0 V		1300		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs		16	_	μC

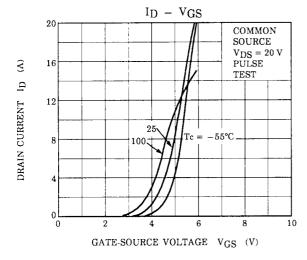
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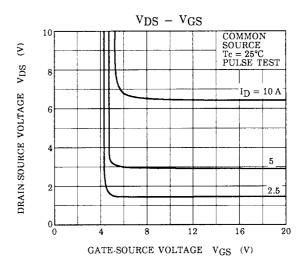


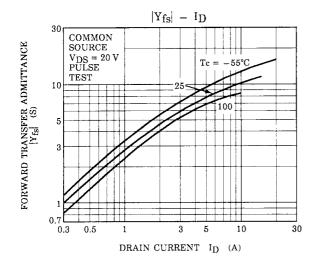
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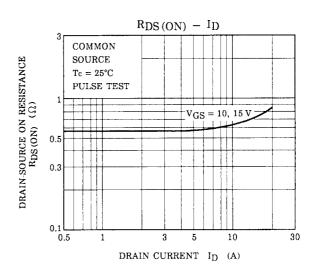




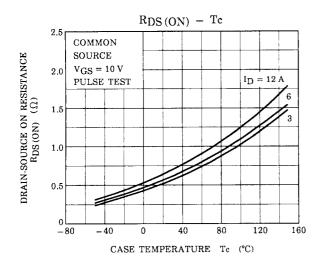


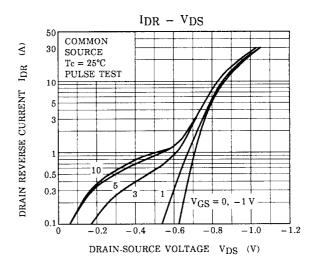


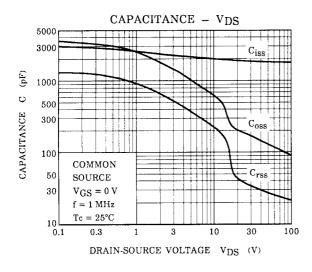


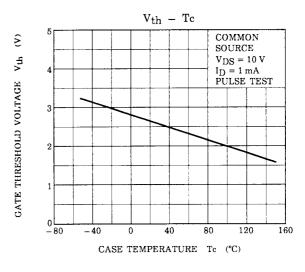


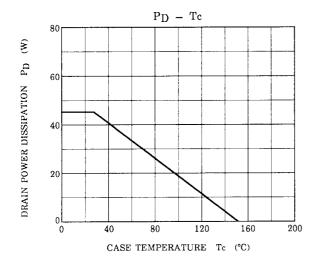
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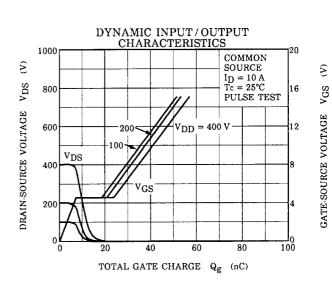




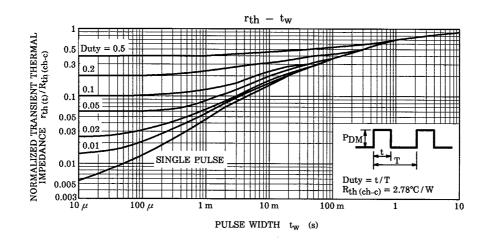


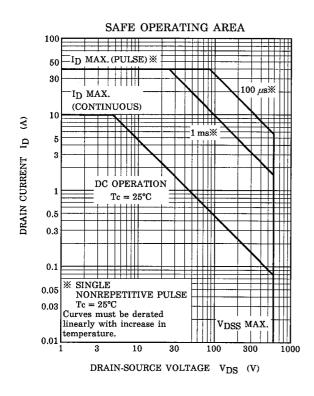


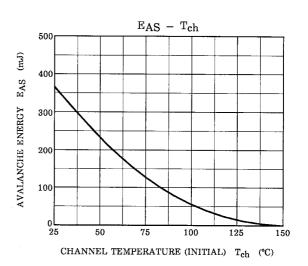


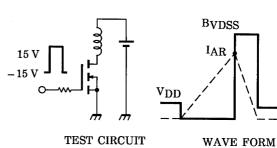


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$$R_G$$
 = 25 Ω
 V_{DD} = 90 V, L = 6.36 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

 v_{DS}

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